

Title (en)

METHOD FOR MOUNTING AN ELECTRICAL COIL ON A MAGNETIC CIRCUIT HAVING AN AIR GAP.

Title (de)

VERFAHREN ZUM MONTIEREN EINER ELEKTRISCHEN SPULE AUF EINEM MAGNETKREIS MIT LUFTSPALT.

Title (fr)

PROCEDE DE MONTAGE D'UNE BOBINE ELECTRIQUE SUR UN CIRCUIT MAGNETIQUE A ENTREFER.

Publication

**EP 0584295 A1 19940302 (FR)**

Application

**EP 93901617 A 19930120**

Priority

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- CH 16392 A 19920121

Abstract (en)

[origin: WO9314509A1] Plane sheets which have the same shape as the magnetic circuit (1) and are relatively movable along their contact surface are arranged in a stack. The stack is grasped and part of the circuit is bent out of alignment with the plane of the sheets to enable a coil (3) to be placed on a portion of the circuit which is next to the air gap (2), whereafter said part is bent back into alignment with said sheets.

Abstract (fr)

On réalise un empilage de tôles planes ayant toutes la forme du circuit magnétique (1) et étant déplaçables les unes par rapport aux autres le long de leur surface de contact. On saisit cet empilage et l'on déforme une partie du circuit par rapport au plan des tôles, de façon à permettre la mise en place d'une bobine (3) sur une partie du circuit voisine de l'entrefer (2). On ramène ensuite la partie déformée dans le plan des tôles.

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Citation (search report)

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Cited by

US7332903B2; US7541799B2; US7923986B2

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